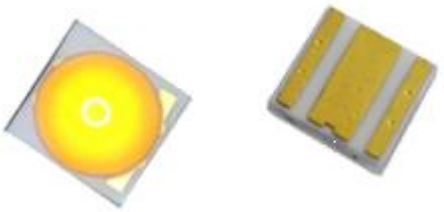
5FDP35AW5FFH0YZ4

- Outline : 3.5*3.5*2.22mm
- High efficiency
- Good thermal dissipation & optical uniformity



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Features

- RoHS2.0 and REACH-compliant
- MSL2 qualified according to J-STD 020
- InGaN based phosphor-converted LED
- ESD 2KV (HBM : MIL-STD-883 Class 2)

Applications

- Portable lighting
- Outdoor lighting
- Indoor lighting
- Commercial lighting
- Industrial lighting
- Decorative lighting
- Automobile lighting
- Street and tunnel lighting

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■ Product Code

5 – F – DP35 – A – W5FF – H – 0 – Y – Z – 4

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

①	②	③	④	⑤
Process type	Category	Specification	Lens Angle code	Dice wavelength & Luminous rank
5:ForAutomotive	F: Flip Chip LED	DP35: Ceramic 3535	A: 120°	W5XX: Warm White

⑥	⑦	⑧	⑨	⑩
Support code	Zener & High CRI	Cap color code	Module & Lens code	Current code
H: HTCC	0: None Zener	Y: 1700K	Z: Molding	4: 350mA

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■ Typical Product Characteristics(Ta=25℃)

Luminous Flux (lm) @350mA			Typical CCT (K)	Forward Voltage (V) @350mA		Viewing Angle
Group	Min.	Max.		Min.	Max.	
B30	75	80	1700	2.8	3.4	120°
B31	80	90				
B32	90	100				
B33	100	110				

Notes:

1. Forward voltage (V_F) ±0.05V ; Luminous flux (Φ_V) ±7% ; Viewing angle($2\theta_{1/2}$) ±10°
2. IS standard testing.

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■ Maximum Rating (Ta : 25℃)

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current[1]	I_F			1000	mA
Pulse Forward Current[2]	I_{PF}			1500	mA
Reverse Voltage	V_R			5	V
Reverse Current	I_R			10	μA
Junction Temperature[3]	T_j			150	℃
Thermal Resistance Junction / Solder Point	R_{th}		10		℃/W
Storage Temperature Range	T_{stg}	-40	–	105	℃
Operating Temperature Range	T_{op}	-40	–	105	℃
Soldering Temperature	T_{sol}			260	℃

Notes:

1. For other ambient, limited setting of current will depend on de-rating curves.
2. D=0.01s duty 1/10.
3. When drive on maximum current , Tj must be kept below 150℃

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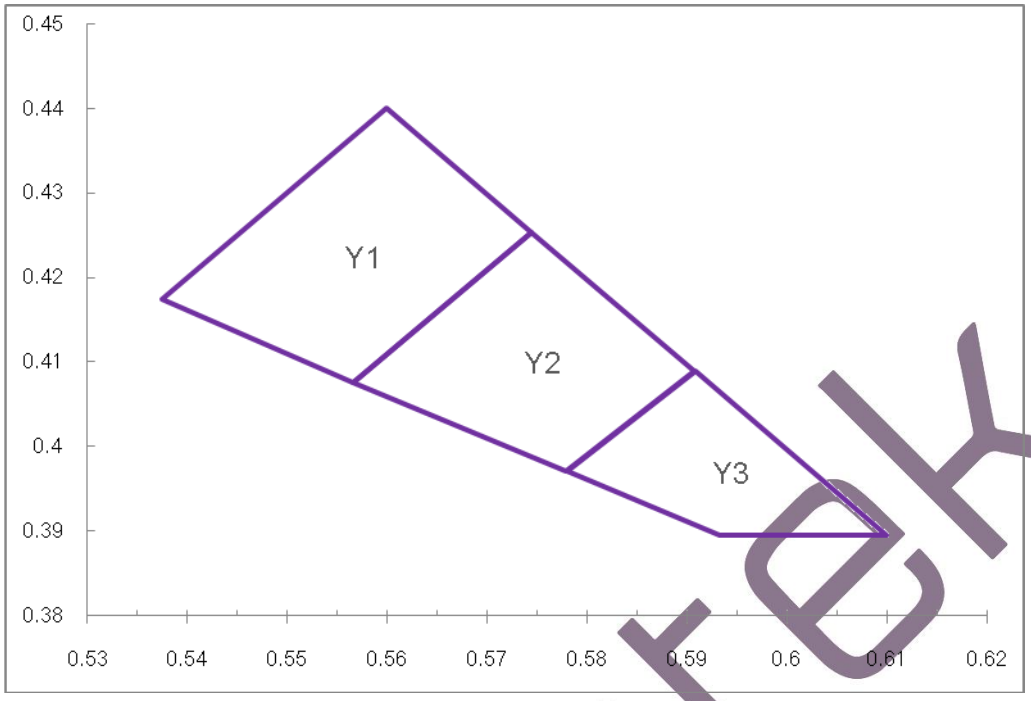
■ Intensity Binning

Bin code (350mA)	Min. Φ_v (Lm)	Max. Φ_v (Lm)
B30	75	80
B31	80	90
B32	90	100
B33	100	110

■ Forward Voltage Binning

Bin code (350mA)	Min. V_F (V)	Max. V_F (V)
V2830	2.8	3.0
V3032	3.0	3.2
V3234	3.2	3.4

■ Color coordinate binning



BIN	CIE X	CIE Y	BIN	CIE X	CIE Y	BIN	CIE X	CIE Y
Y1	0.5600	0.4400	Y2	0.5745	0.4253	Y3	0.5908	0.409
	0.5375	0.4174		0.5566	0.4076		0.578	0.3972
	0.5566	0.4076		0.578	0.3972		0.5933	0.3896
	0.5745	0.4253		0.5908	0.409		0.6100	0.3896

Notes : Chromaticity (CIEx, CIEy) ±0.007

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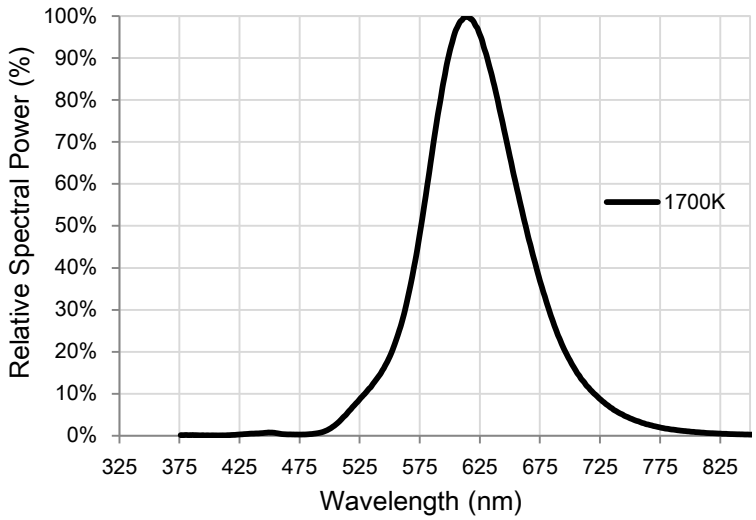
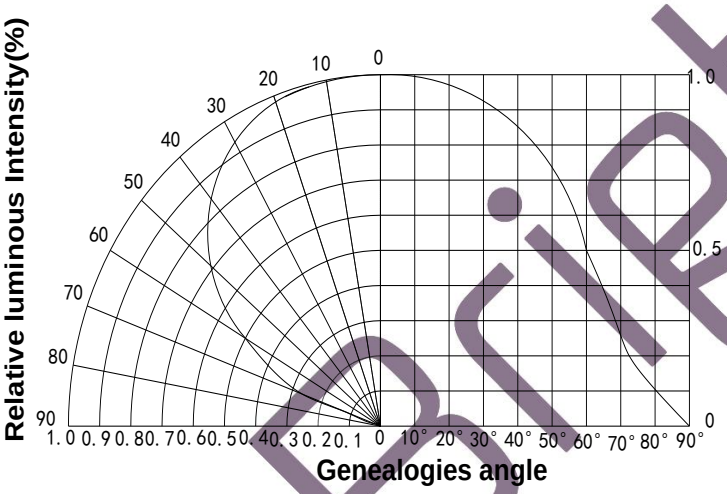
■ Relative spectral power distribution

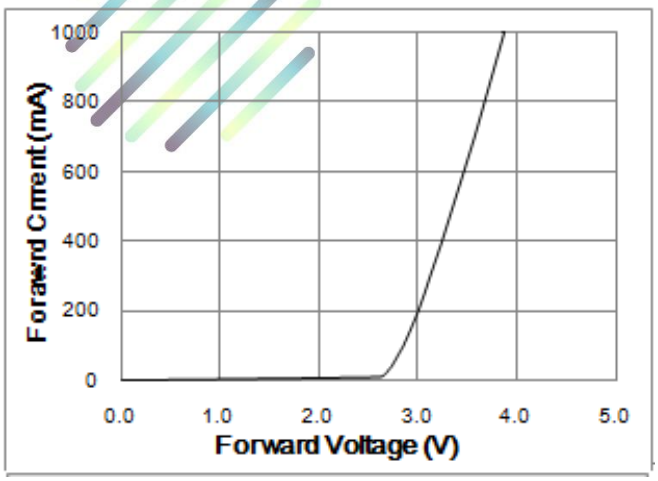


■ Typical Spatial Distribution

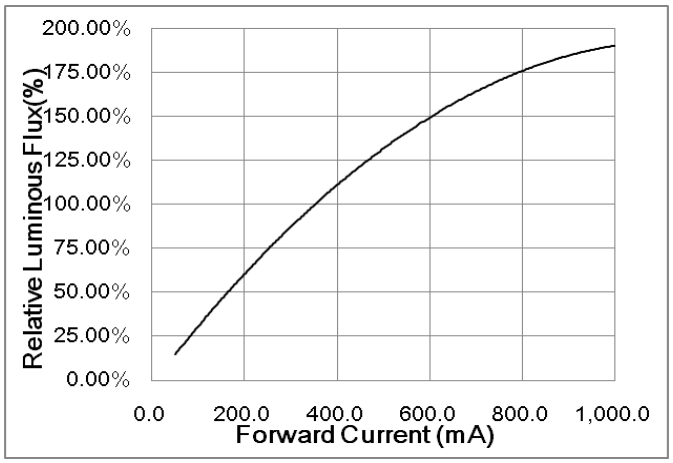


■ Electronic-Optical Characteristics

Forward Current vs. Forward Voltage (Ta=25℃)



Relative luminous Flux vs. Forward Current (T_a=25℃)



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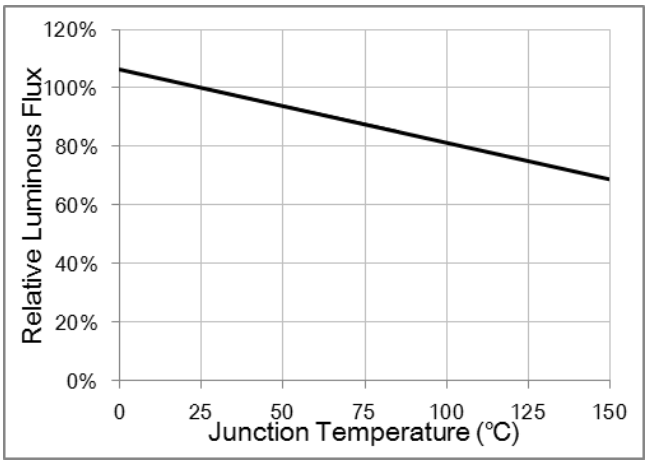
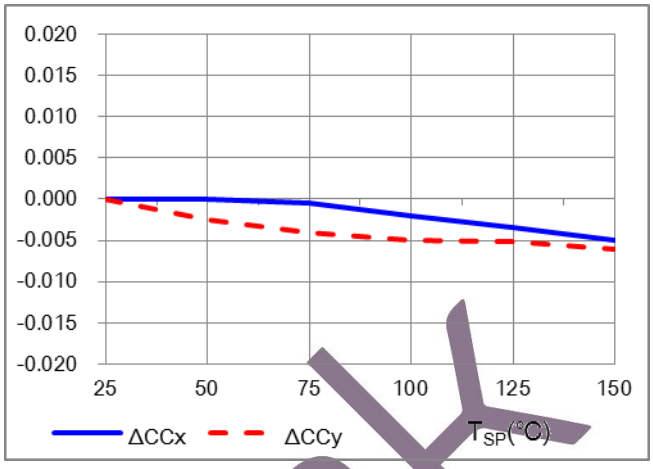
Relative Flux vs. Junction Temperature (I_F=350mA)

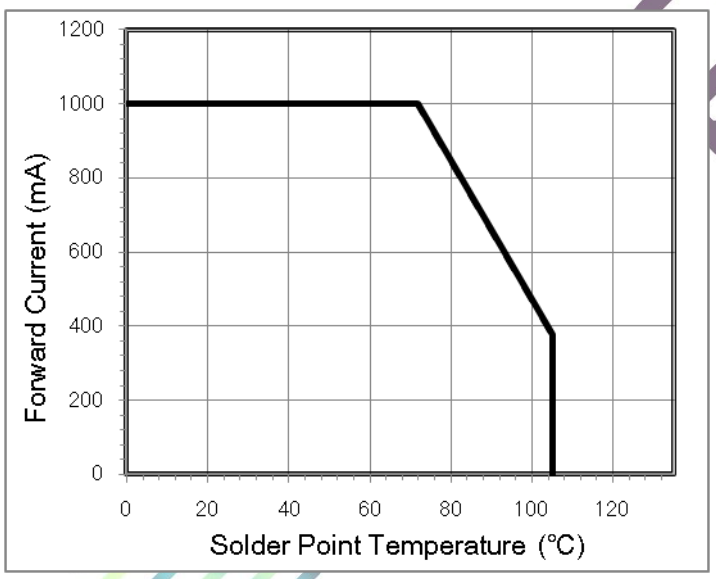


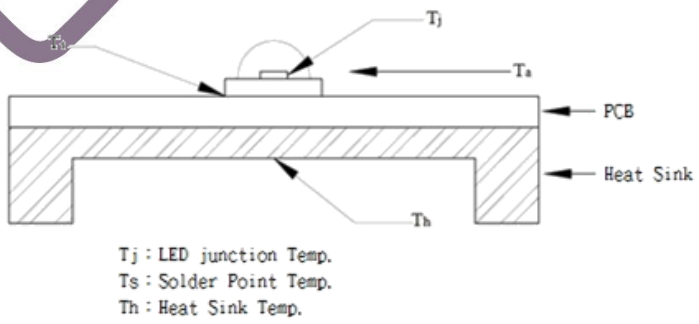
Relative Chromaticity vs. Ambient temperture (I_F=350mA)



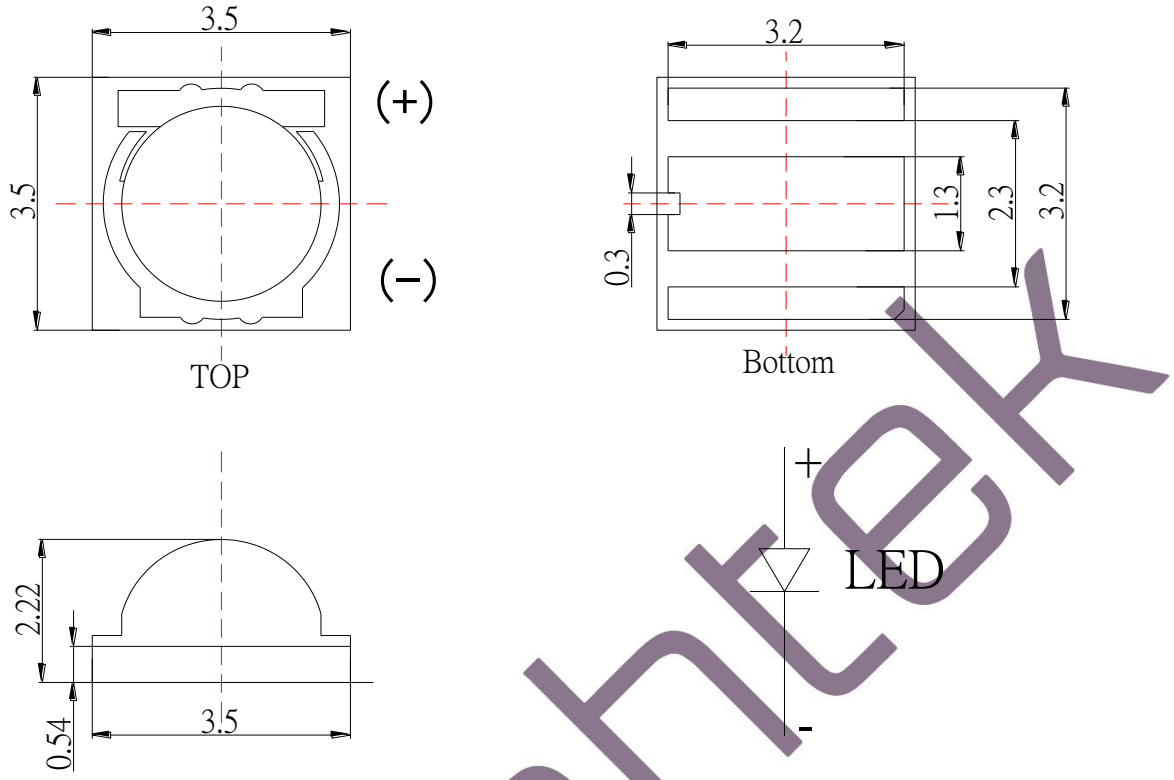
■ Thermal Design for De-rating

The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.





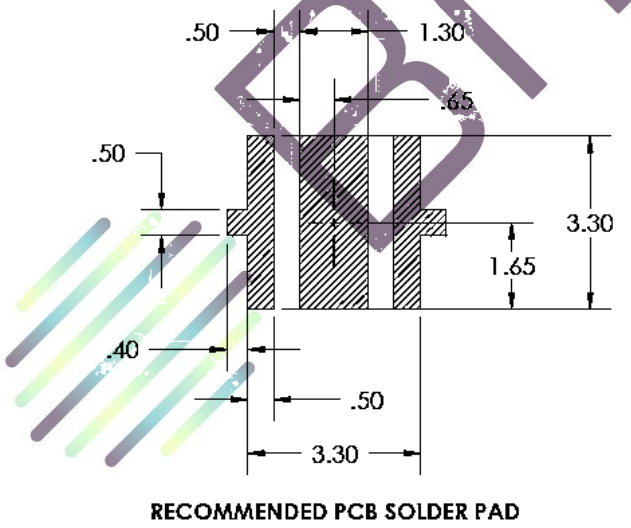
■ Dimensions



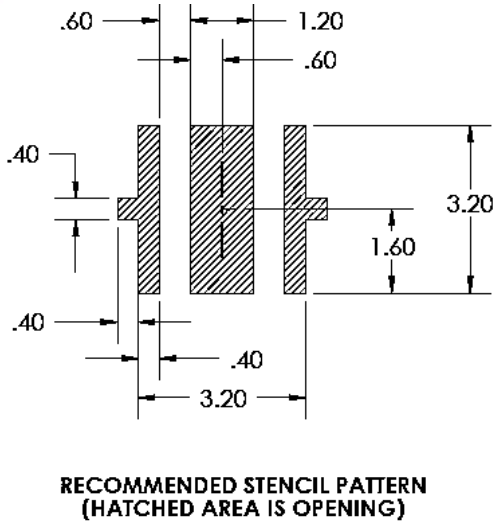
§ All dimensions are in millimeters.

§ Tolerance is ±0.13mm unless other specified.

■ Suggest Stencil Pattern (Recommendations for reference)



RECOMMENDED PCB SOLDER PAD



RECOMMENDED STENCIL PATTERN
(HATCHED AREA IS OPENING)

§ Suggest stencil t =0.12 mm

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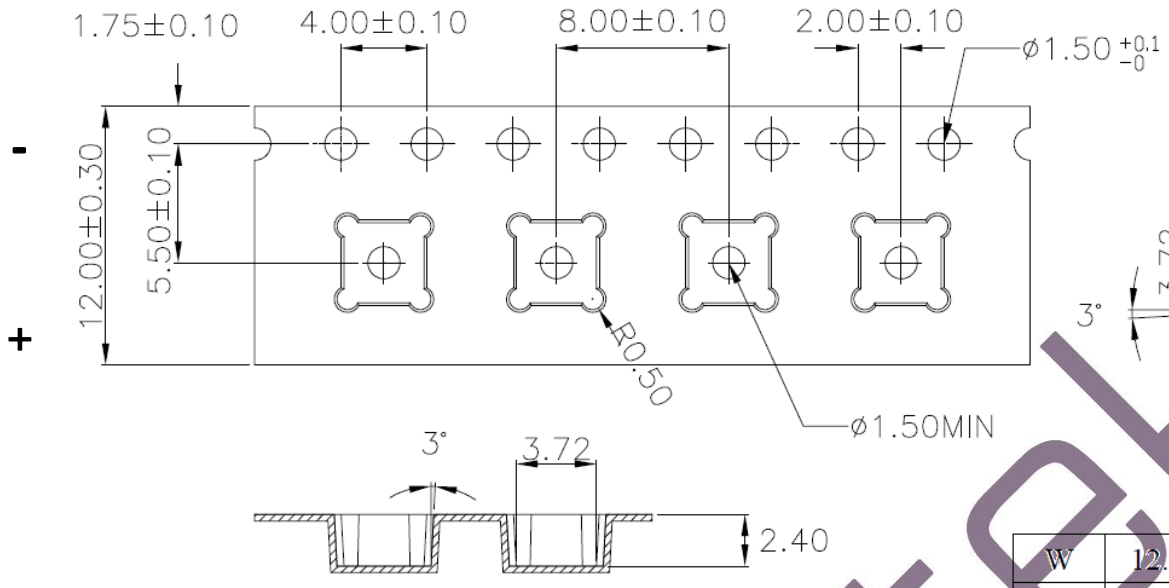
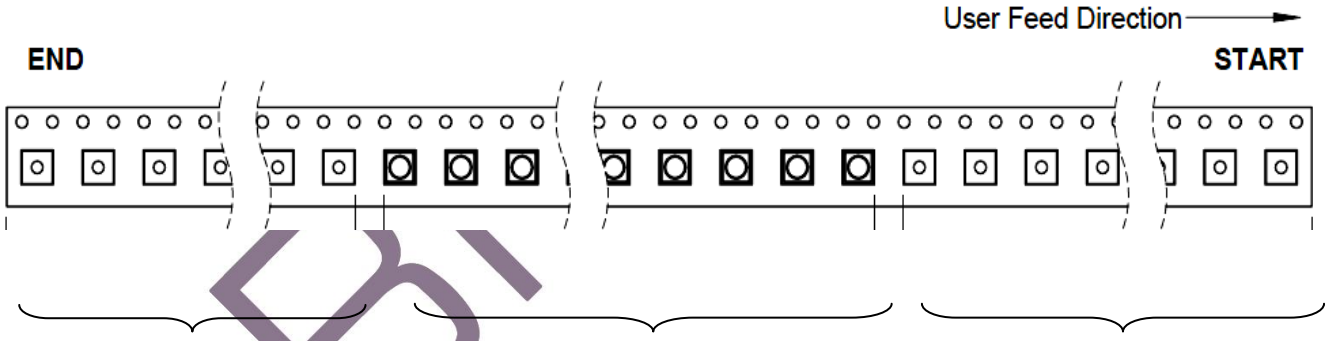
■ Packing



W	12.00±0.30
A0	3.72±0.10
B0	3.72±0.10
K0	2.40±0.10

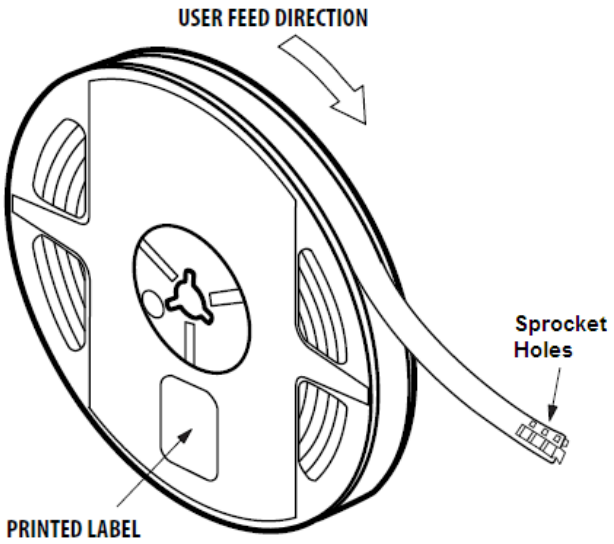
1. 10 sprocket hole pitch cumulative tolerance ±0.20.
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy.
4. All dimensions meet EIA-481-D requirements.
5. Thickness : 0.30±0.05mm.

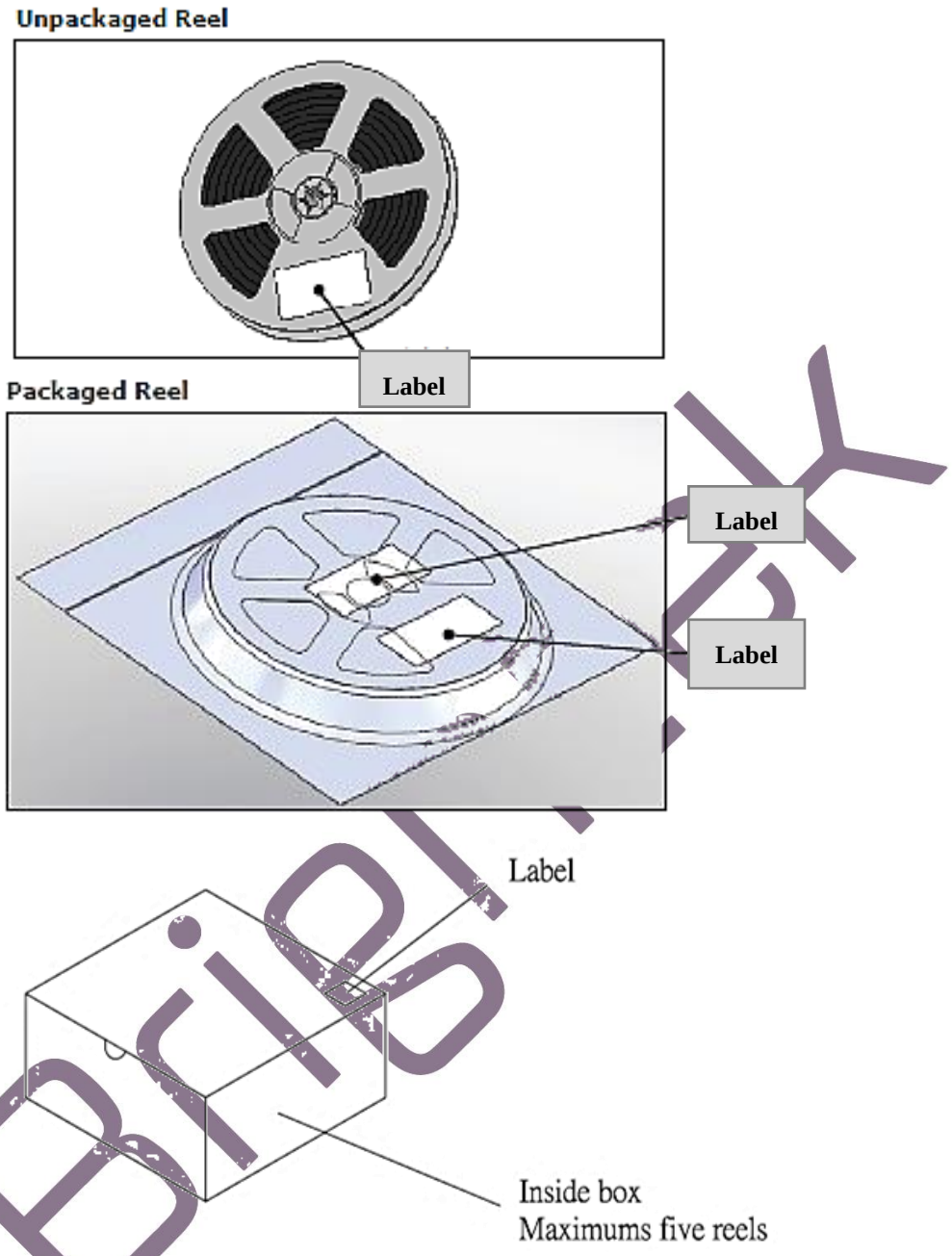


Trailer 160mm (min) of empty pockets sealed

Loaded Pockets (1000 pcs)

Leader 400mm (min) of empty pockets sealed



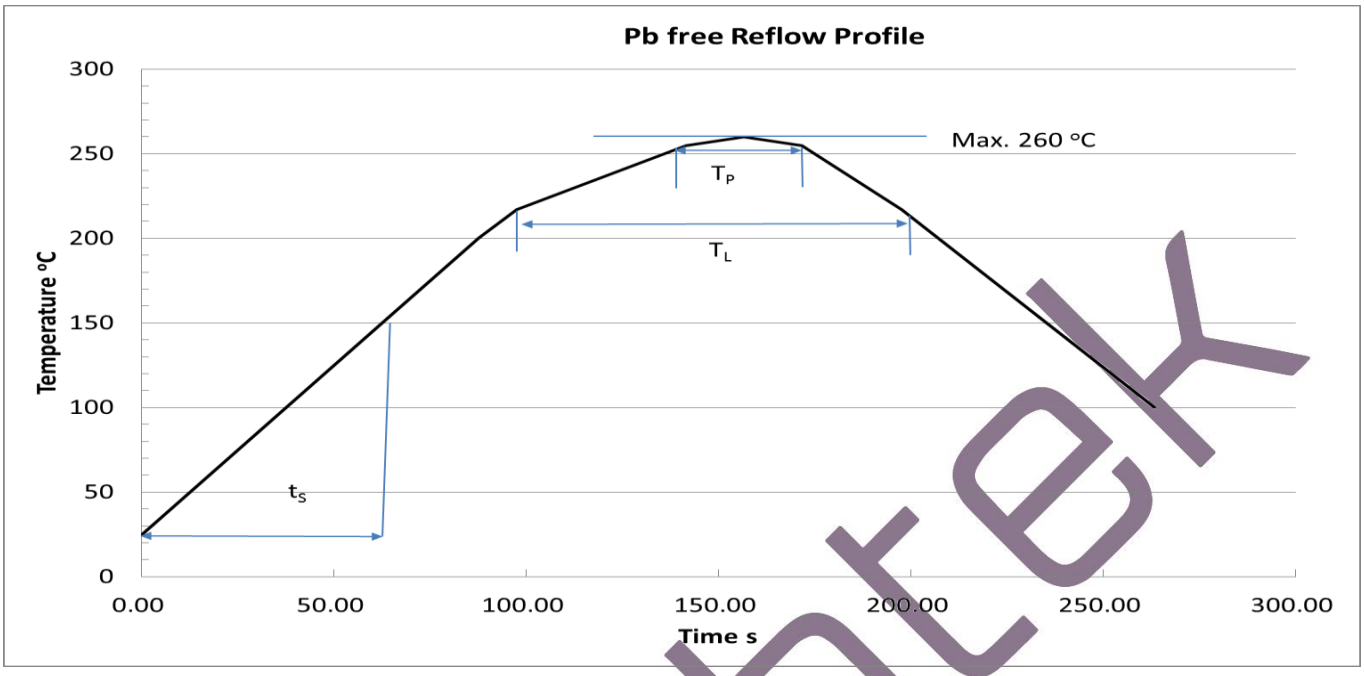


Notes:

1. Each reel (minimum number of pieces is 100 and maximum is 1000 for 120 degree product) is packed in a moisture-proof bag along with a packs of desiccant and a humidity indicator card.
2. A maximum of 5 moisture-proof bags are packed in an inner box (size: 260mm x 230mm x 100mm ±5mm).
3. A maximum of 4 inner boxes are put in an outer box (size: 480mm x 275mm x 215mm ±5mm).
4. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.

■ Reflow Profile

IR Reflow Soldering Profile



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up Rate to Preheat (25°C to 150°C)			2	3	K/s
Time t_S (T_{Smin} to T_{smax})	t_S	60	100	120	s
Ramp-up Rate to Peak (T_{Smax} to T_P)			2	3	K/s
Liquidus Temperature	T_L		217		°C
Time above Liquidus temperature	t_L		80	100	s
Peak Temperature	T_P		245	260	°C
Time within 5 °C of the specified Peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down Rate (T_P to 100 °C)			3	4	K/s
Time 25 °C to T_P				480	s

Notes:

1. Do not stress the silicone resin while it is exposed to high temperature.

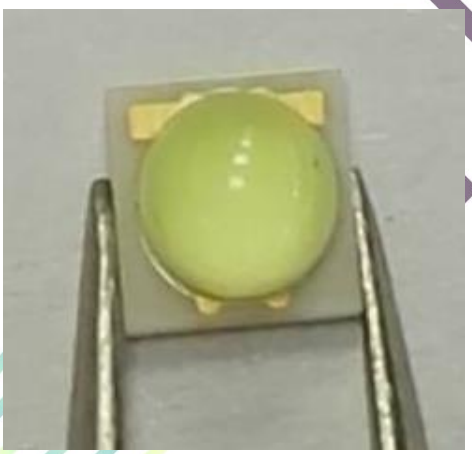
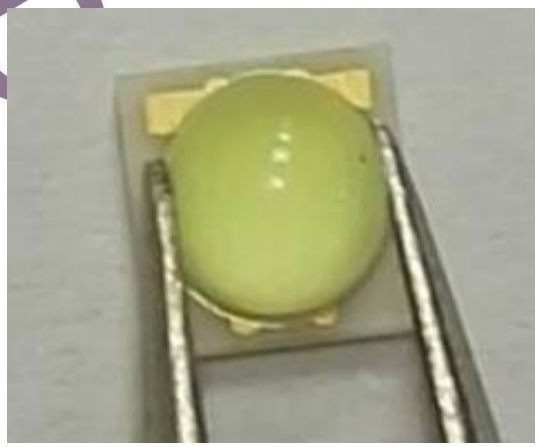
The reflow process should not exceed 2 times.

■ Precautions

1. Recommendation for using LEDs
   - 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
   - 1.2 Avoid mechanical stress on LED lens.
   - 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
   - 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging

2. Lens handling

   Please follow the guideline to pick LEDs.
   - 2.1 Use tweezers to pick LEDs.
   - 2.2 Do not touch the lens by using tweezers.
   - 2.3 Do not touch lens with fingers.
   - 2.4 Do not apply more than 4N (400gw) directly onto the lens.

Correct (√)	Wrong (X)
	

3. Lens cleaning

   In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.
   - 3.1 Try a gentle wiping with dust-free cloth.
   - 3.2 If needed, use dust-free cloth and isopropyl alcohol to gently clean the dirt from the lens surface.

3.3 Do not use other solvents as they may directly react with the LED assembly.

3.4 Do not use ultrasonic cleaning which will damage the LEDs.

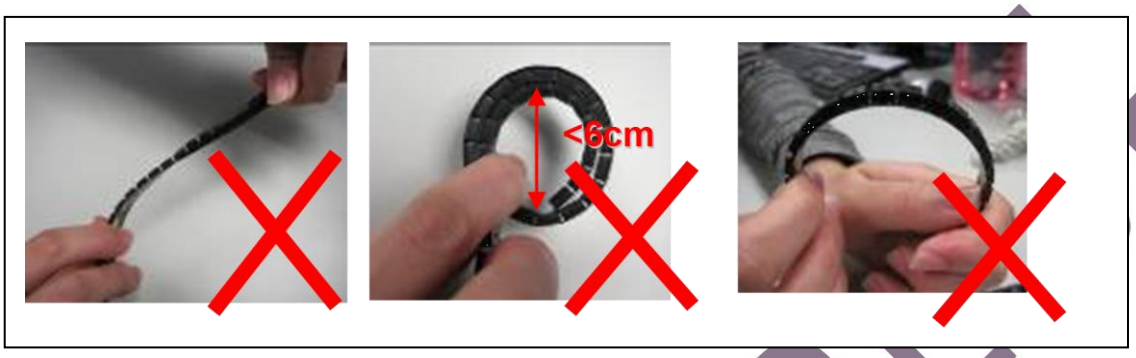
4. Carrier tape handling

The following items are recommended when handling the carrier tape of LEDs.

4.1 Do not twist the carrier tape.

4.2 The inward bending diameter should not be smaller than 6cm for each carrier tape.

4.3 Do not bend the tape outward.



5. Storage

5.1 The moisture-proof bag is sealed：

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

5.2 The moisture-proof bag is opened：

The LEDs should be stored at 30°C or less and 60%RH or less. Moreover, the LEDs are limited to solder process within 168hrs. If the humidity indicator card shows the pink color in 10% even higher or exceed the storage limiting time since opened, that we recommended to baking LEDs at 60°C at least 24hrs. To seal the remainder LEDs return to the moisture-proof bag, it’s recommended to be with workable desiccants.

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■ Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	–40℃ 30min ↑↓5min 125℃ 30min	1000 cycles	0/77	AEC-Q101
High Temperature Storage	T_a=105℃	1000 hrs	0/22	EIAJ ED-4701 200 201
Humidity Heat Storage	T_a=85℃ RH=85%	1000 hrs	0/22	EIAJ ED-4701 100 103
Low Temperature Storage	T_a=-40℃	1000 hrs	0/22	EIAJ ED-4701 200 202
Life Test	T_a=25℃ If=350mA	1000 hrs	0/22	
High Humidity Heat Operation	85℃ RH=85% If=350mA	1000 hrs	0/22	
High Temperature Operation	T_a=105℃ If=350mA	1000 hrs	0/22	
ESD(HBM)	2KV at 1.5kΩ;100pf	3 Times	0/22	MIL-STD-883

Failure Criteria				
Item	Symbol	Condition	Criteria for Judgment	
			Min	Max
Forward Voltage	V_F	If=350mA	-	USL[1]×1.1
Reverse Current	I_R	V_R =5V	-	100μA
Radiant Power	Iv	If=350mA	LSL[2]×0.7	-

Notes:

1. USL: Upper specification level
2. LSL: Lower specification level

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